



Today's Presentation

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Theory & Design



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MEMS Comb Drive Actuator to Vary Tension & Compression of a Resonating Nano-Doubly Clamped Beam for High-Resolution & High Sensitivity Mass Detection



GROUP D

Adam Hurst¹

John Regis¹

Chou Ying-Chi¹

Andrew Lie²

Adrian Podpirka³

1. Graduate Student in Mechanical Engineering, Columbia University
2. Undergraduate in Mechanical Engineering, Columbia University
3. Undergraduate in Material Science and Engineering, Columbia University



Overview

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Today's presentation will cover the following:

- Application & Functionality
- Types of Actuators
- Theory behind selected Actuator
- Thermal Time Constant
- Fabrication
- Packaging
- Questions





NEMS Resonating Beam

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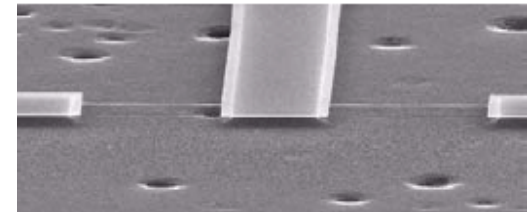


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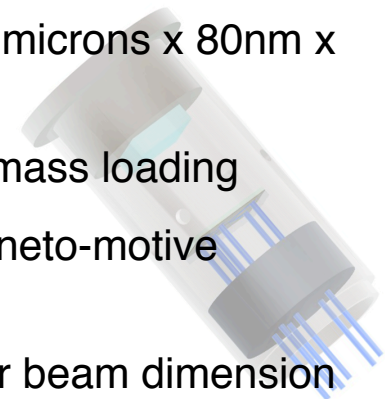
• Applications

- Hyper-sensitive mass detector (hydrogen sensor)
- Anti bio-terrorism (organic compound sensor)
- Mechanical signal processing
- Parametric Amplification



• Functionality

- NEMS Doubly-clamped Au/Pd beam (10 microns x 80nm x 100nm)
- Resonant frequency shifts as a result of mass loading
- Detection of frequency shift through magneto-motive technique
- Frequency shift corresponds to loading or beam dimension changes





MEMS Device for Adjusting Tension of NEMS Resonators

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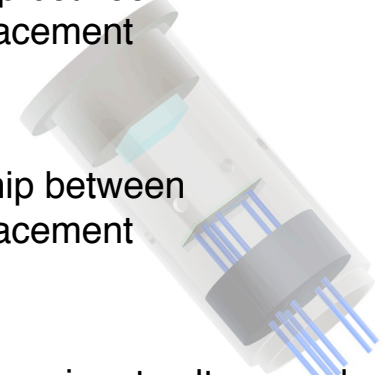


• Motivation

- Residual tensile stresses in beam due to fabrication
- Increased sensitivity under compressive loading
- Desired loading +/- 200Mpa

• MEMS Actuators

- Capacitance-driven electrostatic actuator
 - Advantage: Easy fabrication
 - Disadvantage: Non-linear relationship between input voltage and resultant force/displacement
- Magneto-motive actuator
 - Disadvantage: Semi-linear relationship between input voltage and resultant force/displacement
- **Comb drive electrostatic actuator**
 - Advantage: Linear relationship between input voltage and resultant force/displacement, simple fabrication





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Proposed Comb Drive Design

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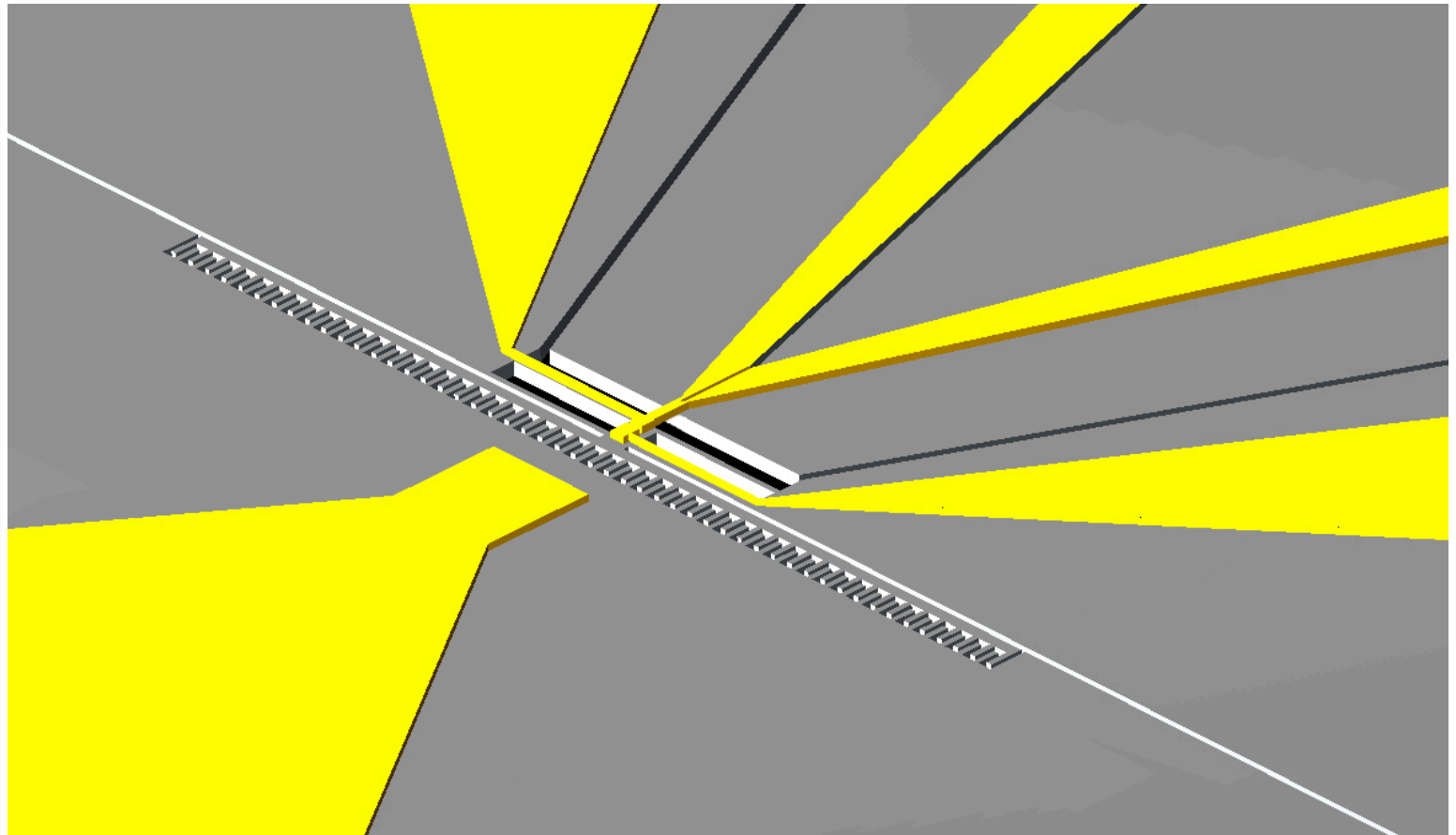
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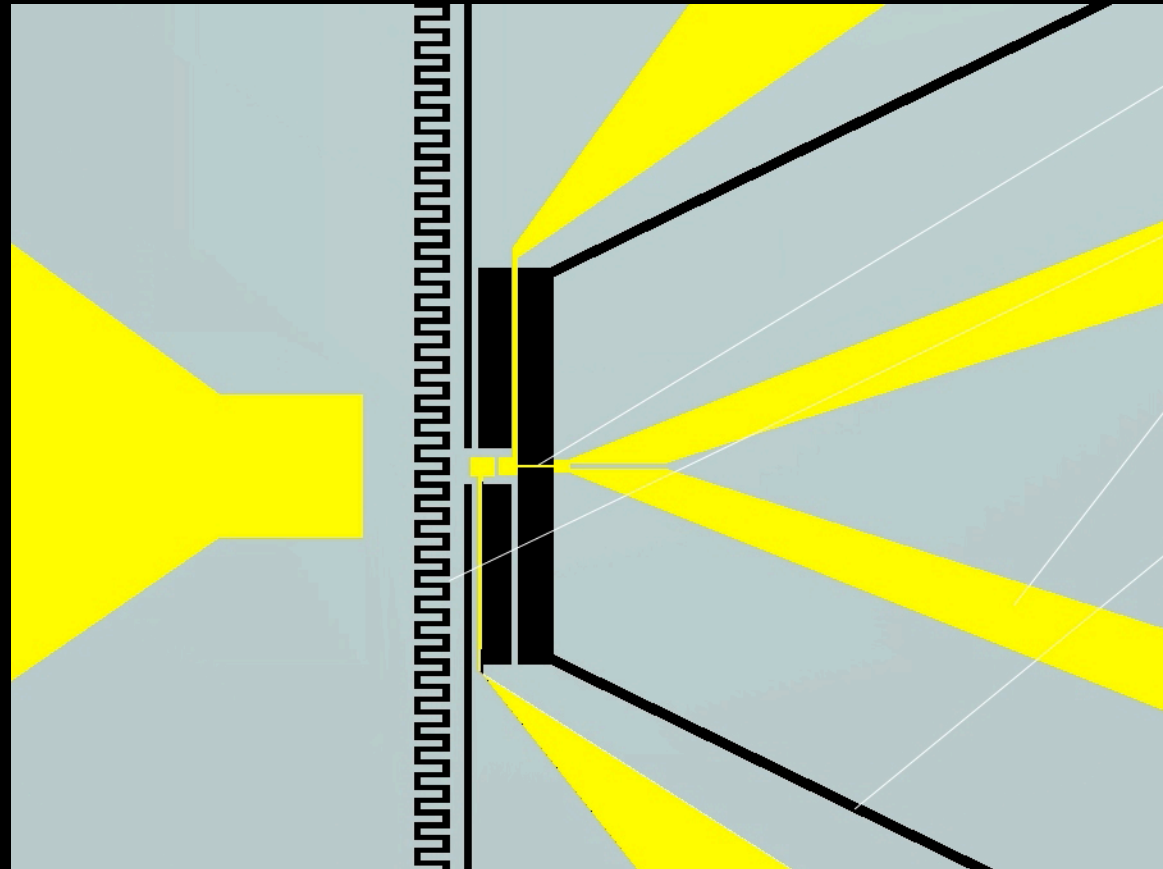
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Resonating Gold Beam

Comb Drive

Gold Contacts

Areal Insulating Spacers



Theory & Design of Comb Drive Electrostatic Actuator

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Resonating Beam Equations:

Required Force on beam is given by: ($P = \pm 200 \text{ MPa}$)

$$P = \frac{F}{A_{Au/Pd}} \longrightarrow F = 1.6 \text{ micro N}$$

Beam axial deflection under $\pm 200 \text{ MPa}$:

$$E_{eAu/Pd} = \frac{E_{Au} A_{Au} + E_{Pd} A_{Pd}}{A_{Au} + A_{Pd}}$$

$$\Delta L = \frac{\sigma}{E_{Au/Pd}} L_0 \longrightarrow L = 25.6 \text{ nm}$$





Theory & Design of Comb Drive Electrostatic Actuator

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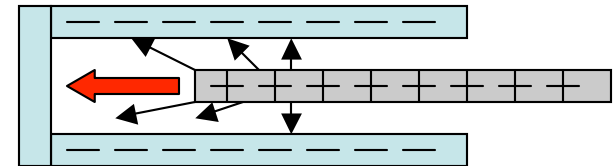
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Comb Drive Equations:

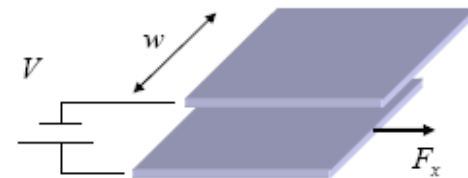
Energy in charged parallel plates:

$$U = \frac{1}{2} \frac{\epsilon_r \epsilon_0 A V^2}{d}$$



Differentiating with respect to x (lateral direction):

$$F_x = \frac{\epsilon_r \epsilon_0 w V^2}{d}$$





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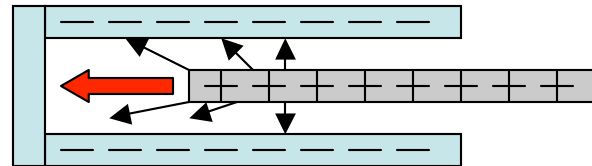
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Comb Drive Equations:

Side Instability Voltage:

$$V_{SI} = \frac{d^2 k_y}{2\epsilon_o b n} \left(\sqrt{2 \frac{k_x}{k_y} + \frac{y_o^2}{d^2}} - \frac{y_o}{d} \right)$$



Beams supporting suspended comb drive resonator structure:

$$k_x = \frac{4E_e b h^3}{L^3}$$

$$F_x = k_{eff} \cdot x$$

$$v(x) = \frac{F}{6E_{eAu/Pd} I} (3x^2 L - x^3)$$

(Assumed to be cantilever beams)



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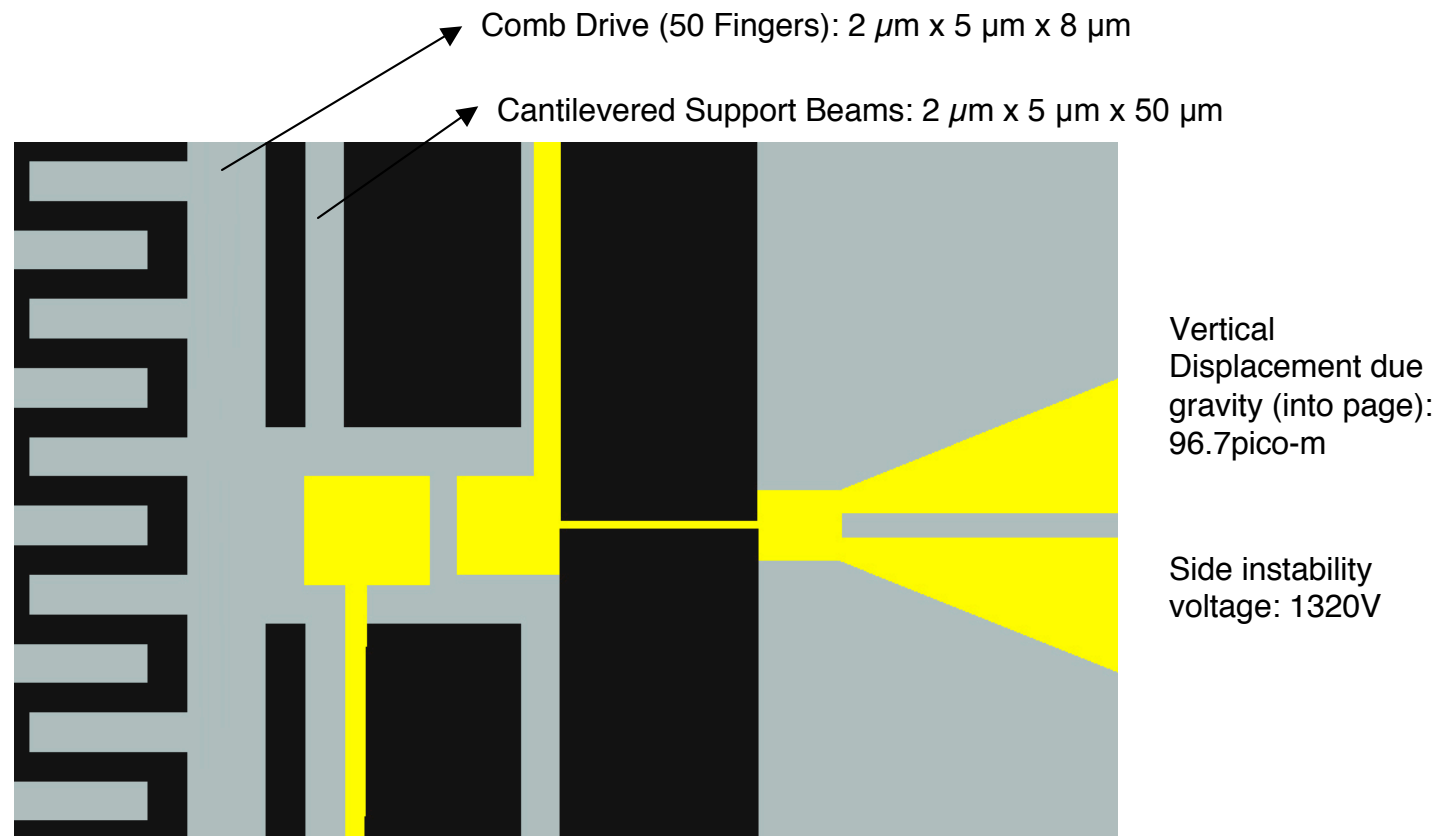
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Critical Dimensions Based on Governing Equations:





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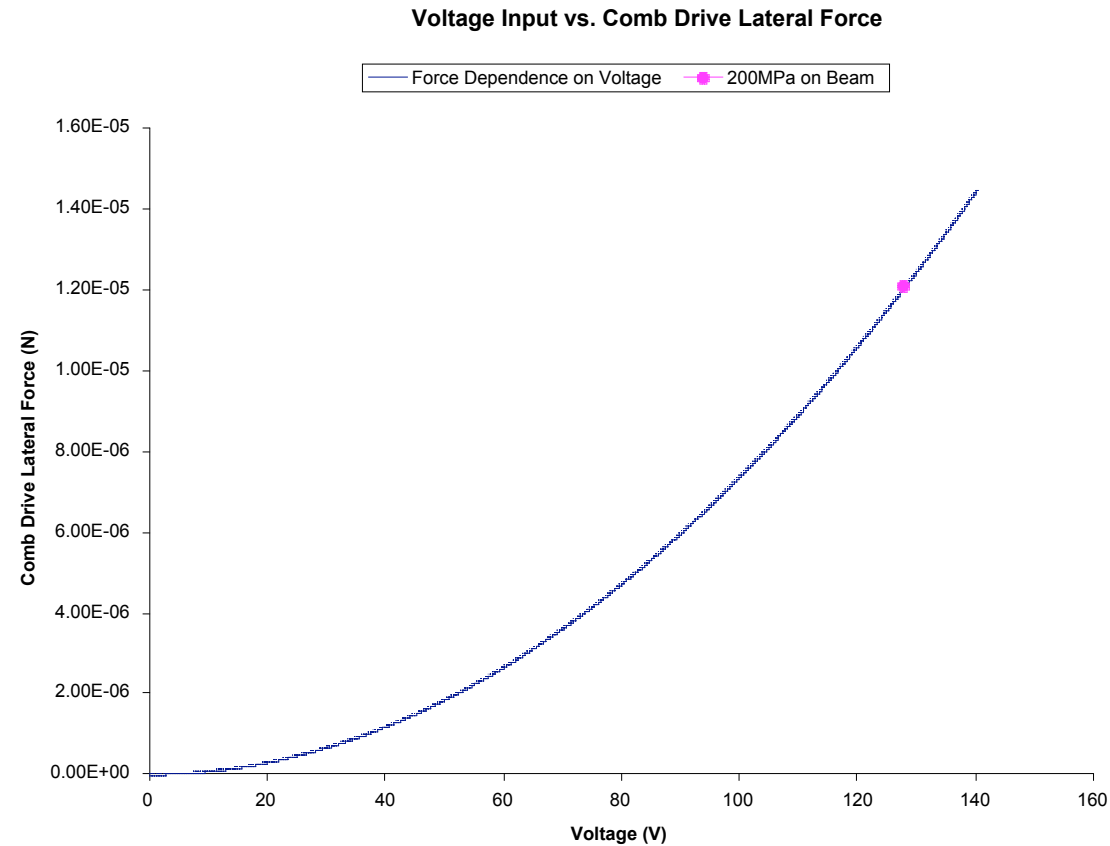
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Voltage Input vs. Force:





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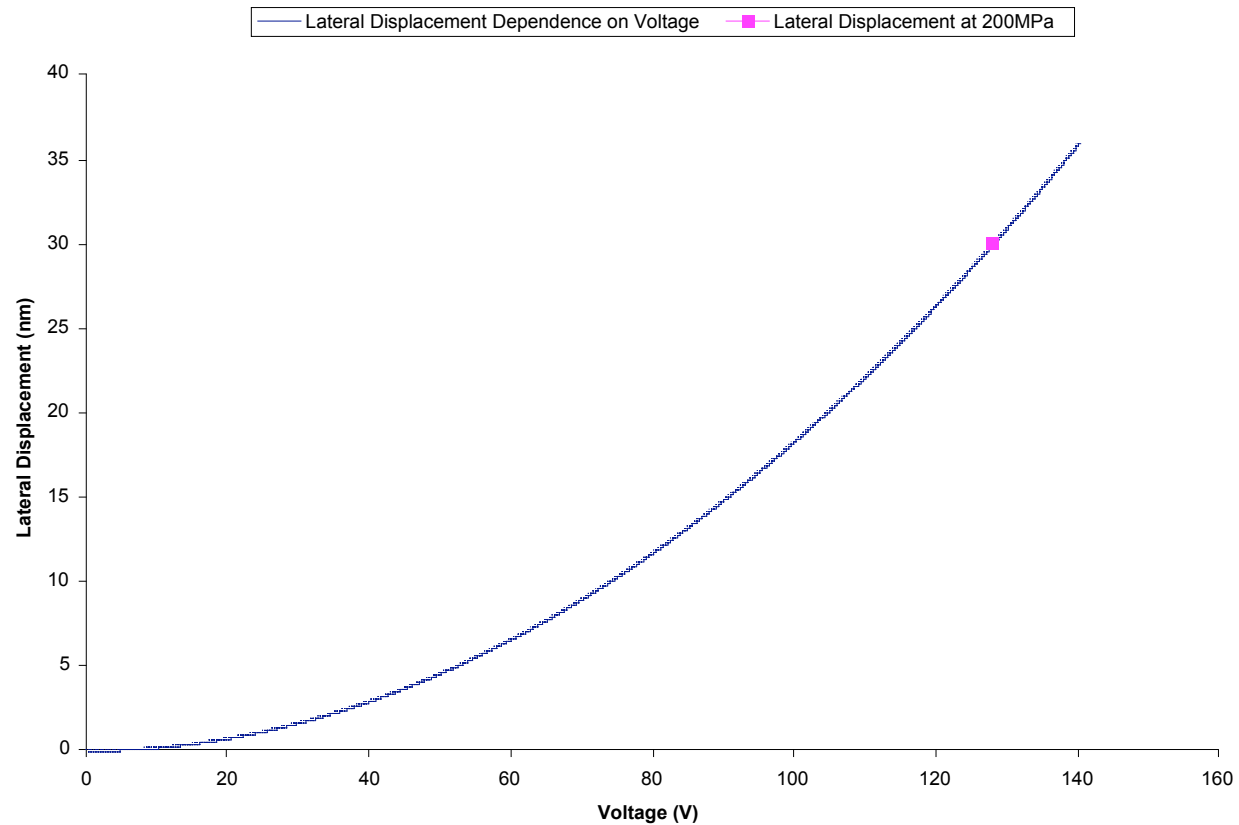


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Voltage Input vs. Lateral Displacement:

Voltage vs. Lateral Displacement





Theory & Design: Thermal Time Constant

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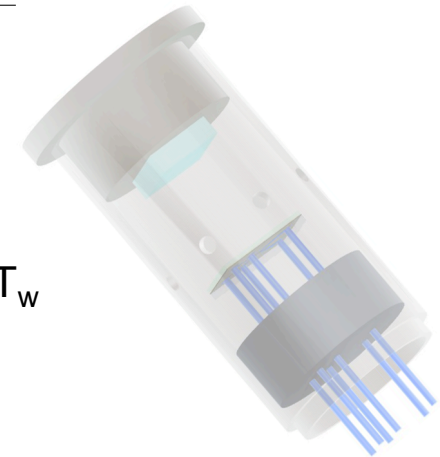
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Thermal Time Constant:

- Thermal time constant of an actuator is the measure of time required for actuator to cool to ambient temperature following actuation.
- Speed at which frequency of the beam can be tuned is highly dependant on time constant.

- Heat Flow Equation:
$$\frac{\partial u}{\partial t} - k \frac{\partial^2 u}{\partial x^2} = \frac{Q(x,t)}{C_p}$$
- Applied DC Current: $I = (I_0)^*(t); I^2 = (I_0)^2*(t)$
Thus, $Q(x,t) = ((I_0)^2*(t)*(R))/(h*w*L)$
- Boundary conditions (1-D): $u(0,t)=T_w; u(L,t)=T_w$
Initial condition: $u(x,0)=T_w$





Theory & Design: Thermal Time Constant

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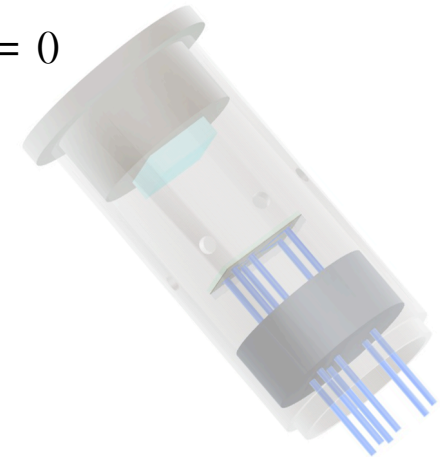
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- New function: $v(x,t)=u(x,t)-T_w$
 $v(0,t)=T_w-T_w=0$; $v(L,t)=T_w-T_w=0$;
 $v(x,0)=T_w-T_w=0$
- New Heat Flow Equation: $\frac{\partial v}{\partial t} - k \frac{\partial^2 v}{\partial x^2} = Q(x,t)$
 $B.C.(1): v(0,t) = 0$
 $B.C.(2): v(L,t) = 0$
 $I.C.: v(x,0) = 0$
- Eigen-function Expansion: $v(x,t) = \sum_{n=1}^{\infty} a_n(t)$
 $where \phi_n(x) =$





Theory & Design of Comb Drive Electrostatic Actuator

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- Sturm-Liouville
- Eigenfunction Expansion \leftrightarrow Heat Flow equation \rightarrow Generalized Fourier Series: $Q(x,t)$.
- Rules of orthogonality (to solve for Fourier coefficients):

$$\frac{da_n}{dt} + \lambda_n k a_n = \frac{\int_0^L Q(x,t) \phi_n(x) dx}{\int_0^L Q_n^2(x) dx} \equiv q_n(t)$$

$$\text{where } Q(x,t) = \sum_{n=1}^{\infty} q_n(t) \phi_n(x)$$

- Orthogonality equation continuous. To make it integratable, use the *Integrating Factor*:

$$e^{-nkt}$$

Fourier Coefficient solved \rightarrow Longest time to reach steady state ($n=1$ eigenmode) \rightarrow Thermal time constant = **0.169 micro-seconds**





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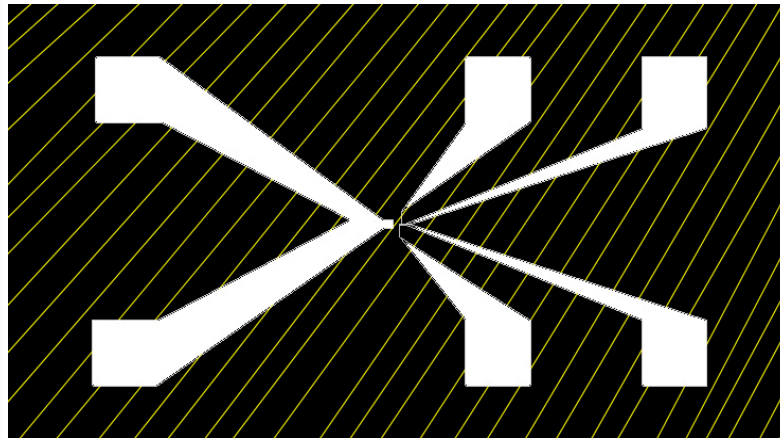
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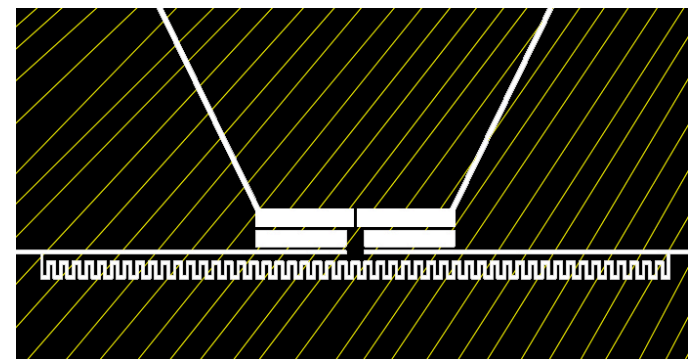
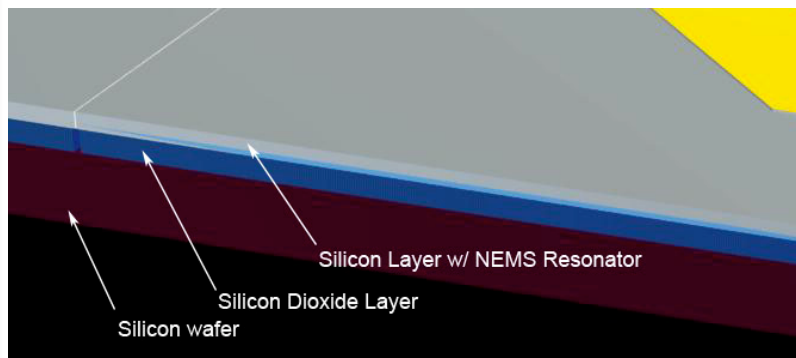
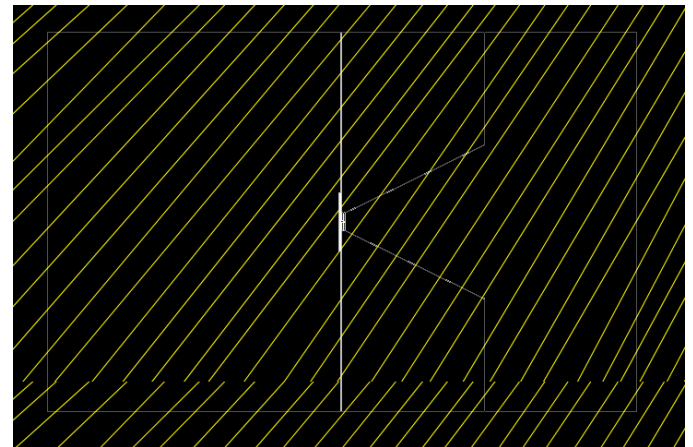
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Mask #1: Au/Pd Contacts and Beam



Mask #2: RIE Comb Drives



Close-Up View



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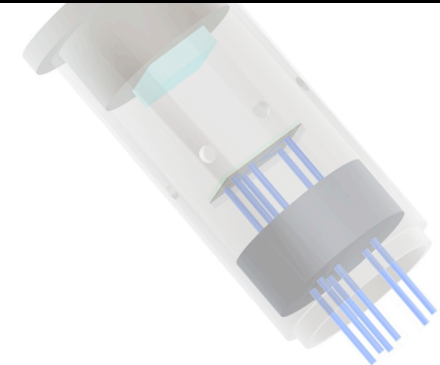
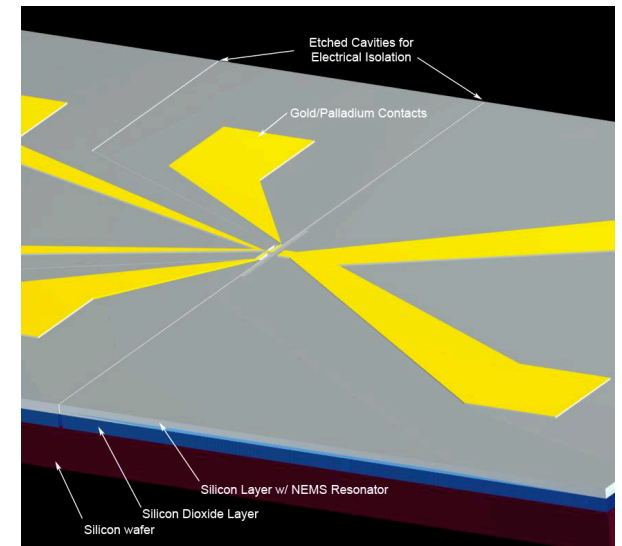


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Process Flow

Step	Description
Starting Material	SOI (5μm-1μm-125μm)
Clean	Standard RCA clean
Photo Resist	Spin on photoresist
Photolithography	Mask #1 (contacts)
develop	Remove area for contact and beam placement
clean	Standard RCA clean
E-beam evap.	Au/Pd e-beam evaporation to a depth of 80nm
strip	Remove photoresist
clean	Standard RCA clean
Photo Resist	Spin on photoresist
Photolithography	Mask #2 (basic structure)
develop	Develop and remove used photoresist
etch	RIE to Silicon Dioxide surface
strip	Remove photoresist
clean	Standard RCA clean
Etch (optional)	Optional - if by using SEM we notice the the underside of the beam is not cut, we will purge the system with XeF2
clean	Standard RCA clean
Etch	5:1 BOE etch
Drying	Supercritical CO2 drying
Clean	Standard RCA clean
Contacts	Place contacts. Wire bond to package.
Test	Test structure
Mount	Pryrex mount
Test	Test structure





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Proposed Comb Drive Design

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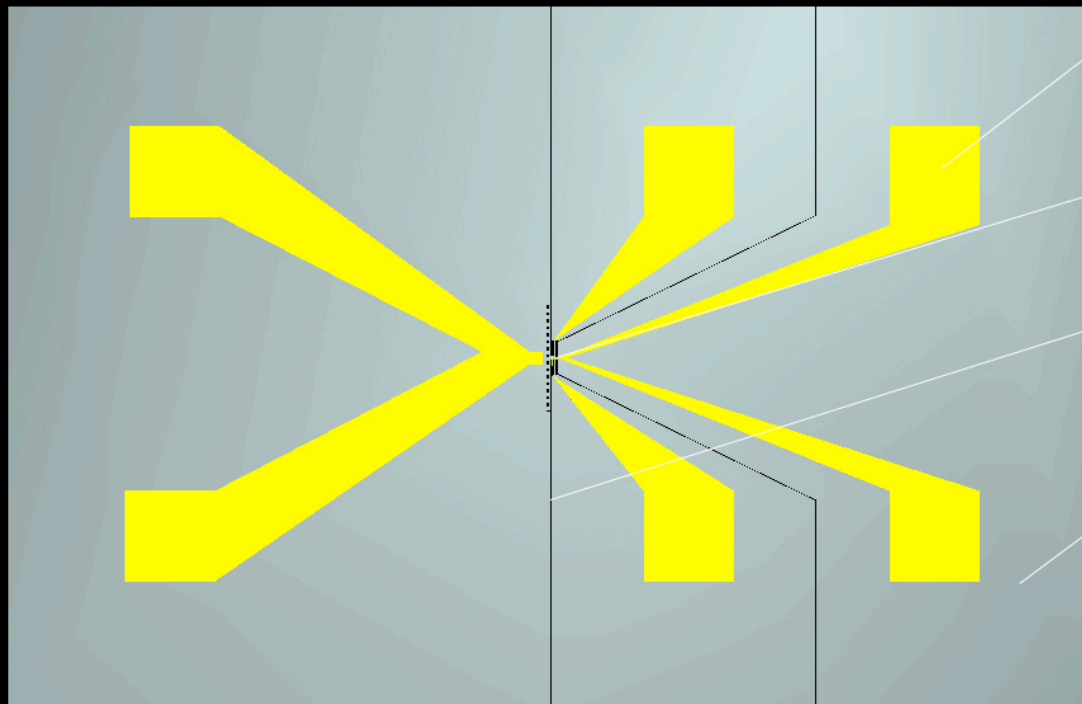
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Gold Contacts

Comb Drive

Areal Insulation
Spacers

Silicon Wafer



Fabrication to Packaging

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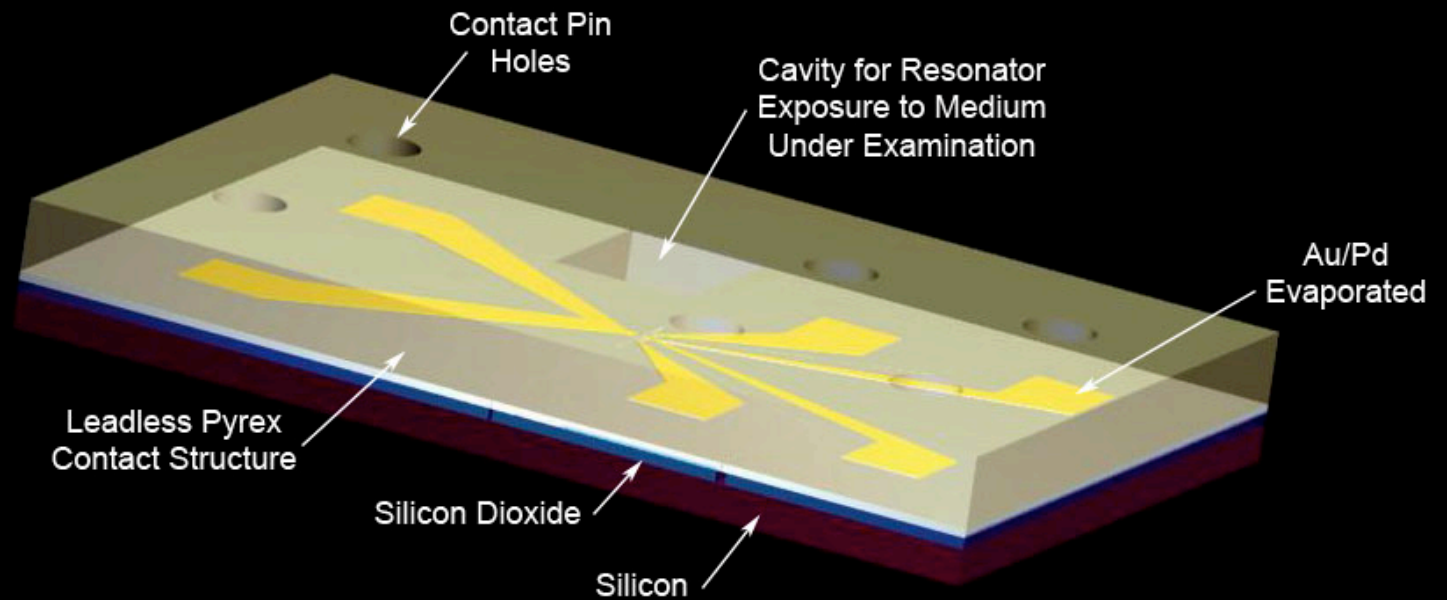
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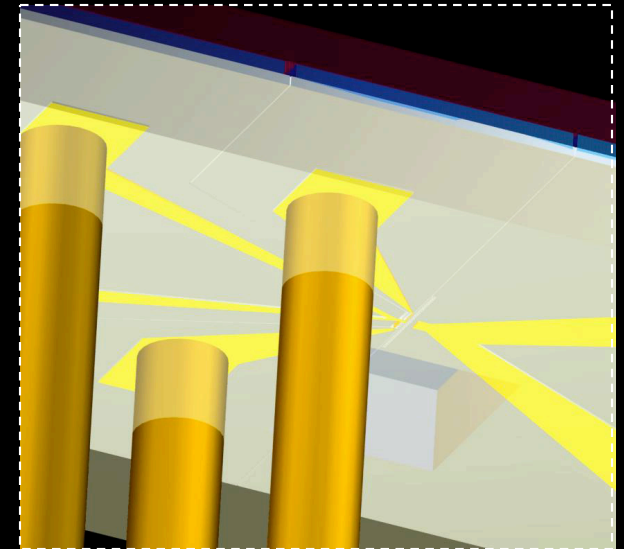
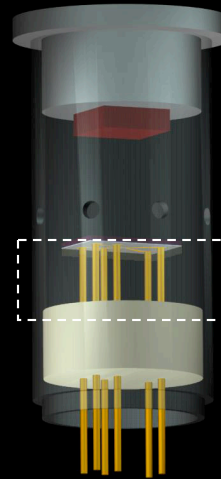
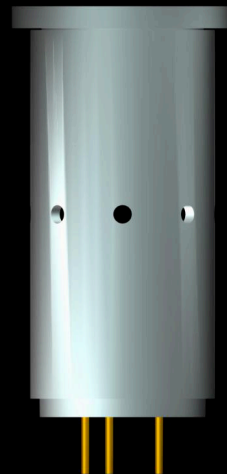
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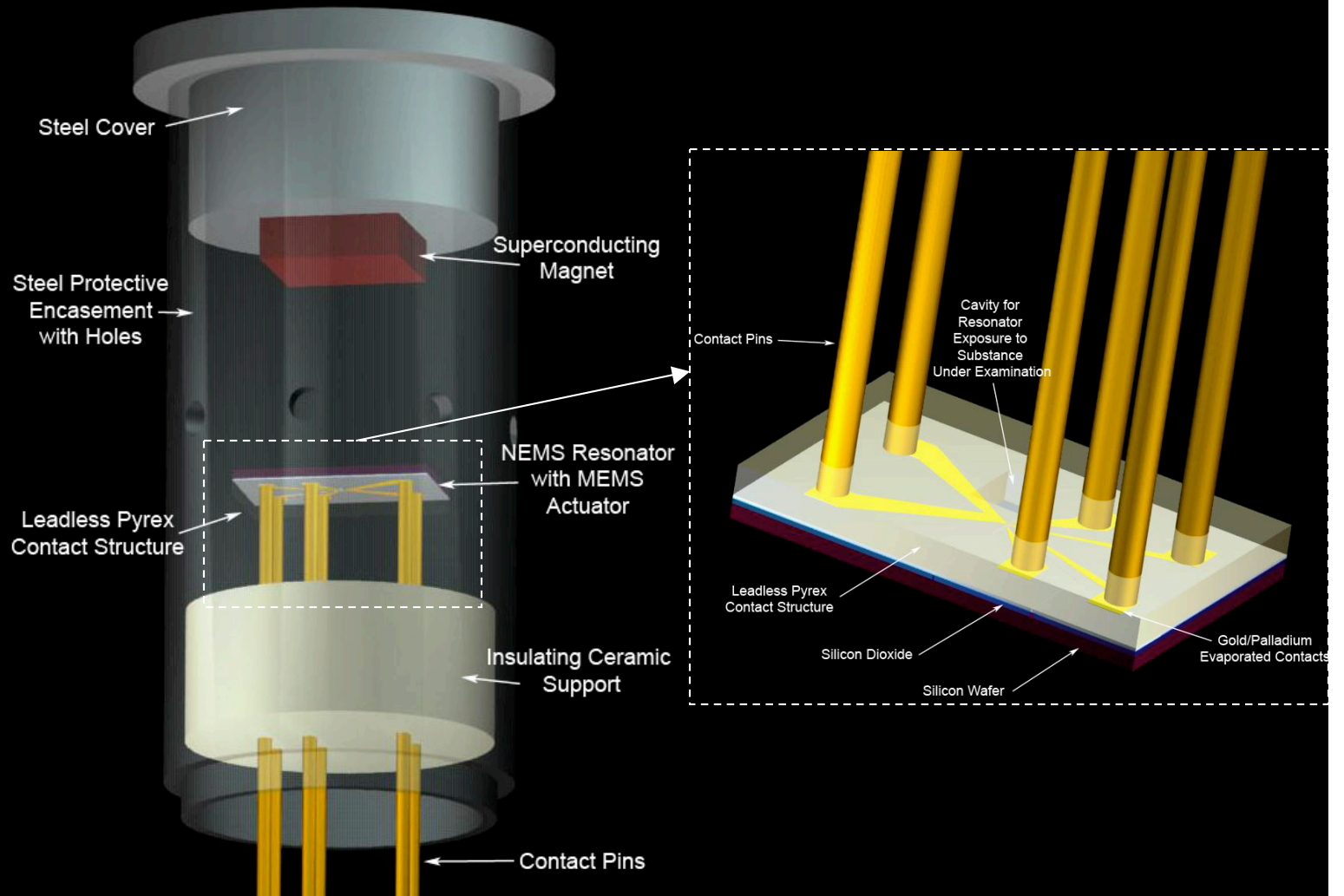
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Conclusion

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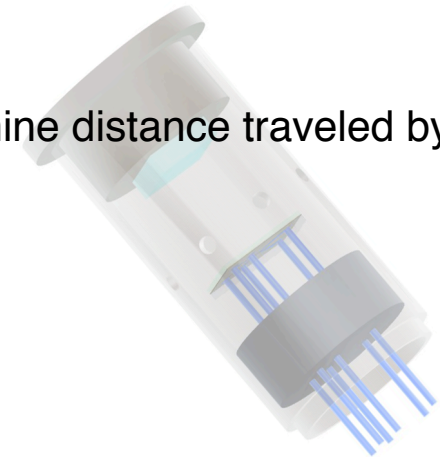
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- For this application, comb-drive actuator is superior to other mechanisms
- Design will allow accurate and feasible application
- Design will be relatively easy to fabricate using Columbia University resources
- Future Improvements: Feed back loop to determine distance traveled by block structure





Acknowledgements & References

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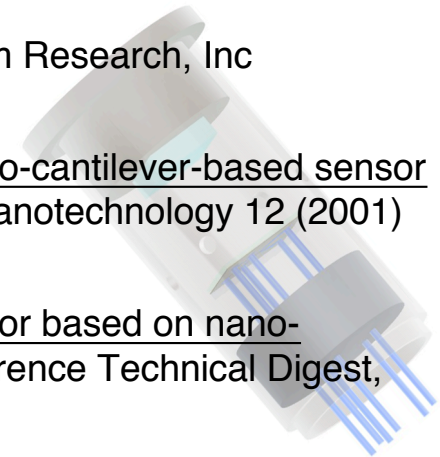
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QUESTIONS?

